

# JTAG\_ADAPTER\_BOARD

## TABLE OF CONTENTS

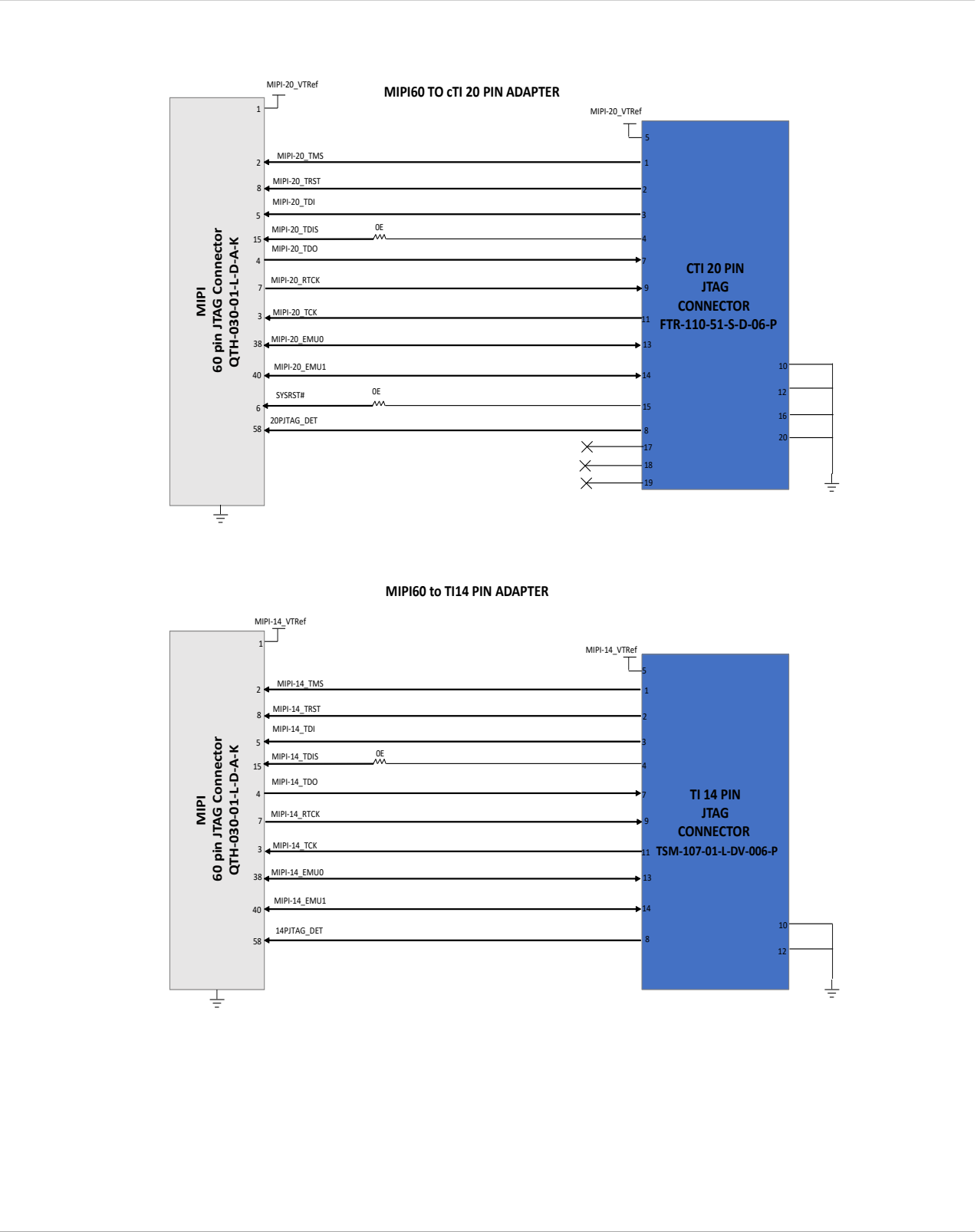
PAGE	CONTENTS
01	TABLE OF CONTENTS
02	BLOCK DIAGRAM
03	MIPI60 to TI14 PIN ADAPTER
04	MIPI60 TO cTI 20 PIN ADAPTER
05	HARDWARE SCHEMATICS

REV	A
VER	0.2

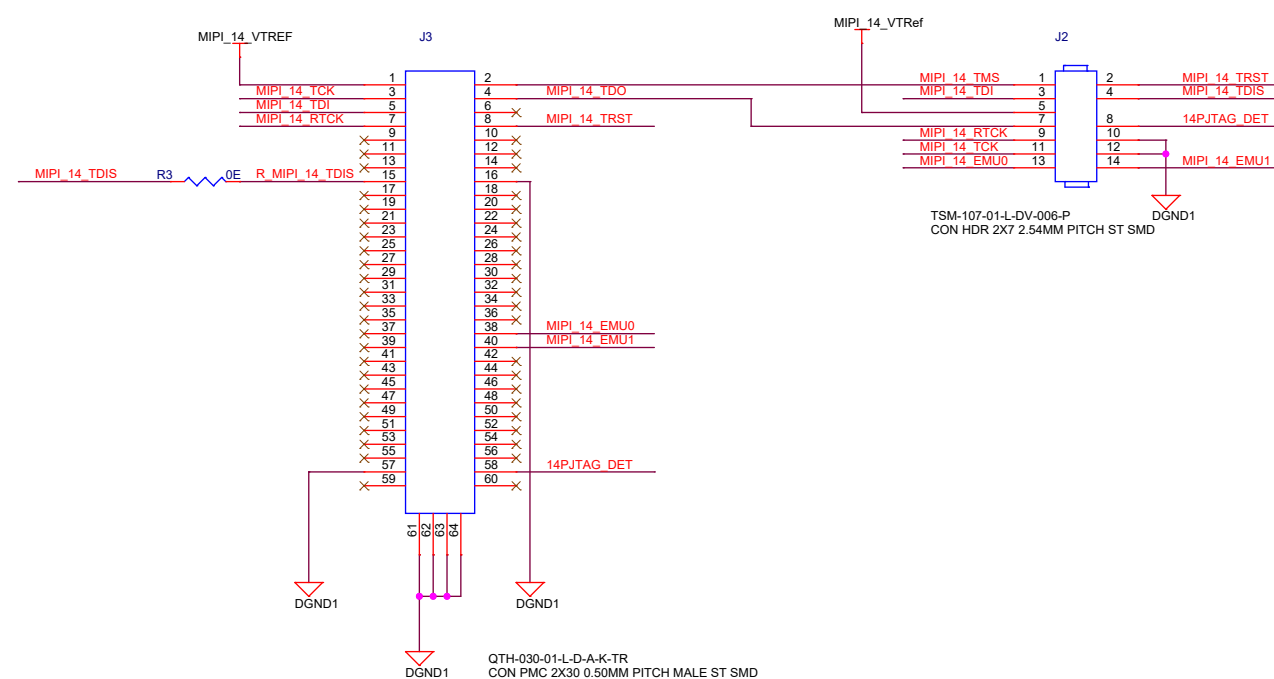
## REVISION HISTORY

VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
0.1	24th JUL 2019	Drafted from "PROC080E2A_SCH, VER: 0.1" PCB Silk screen Information updated PCB Revision updated for "PCB1"	Mistral Design Team		
0.2	29th APR 2022	Drafted from "PROC081E3_SCH, VER: 0.1"	Mistral Design Team		

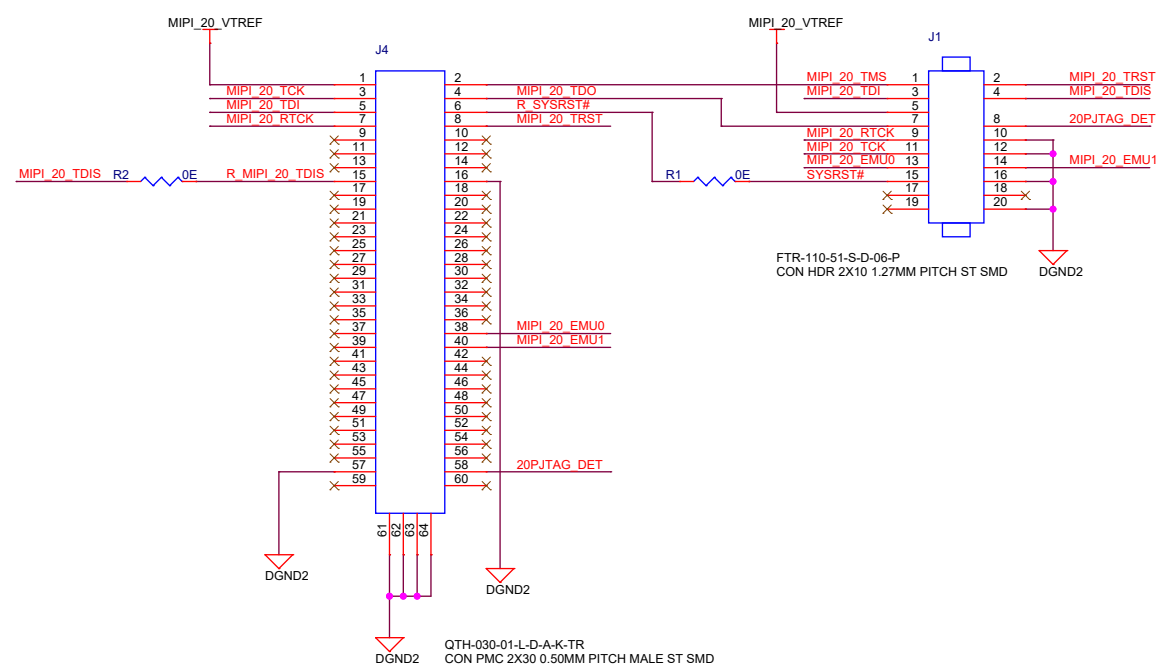
BLOCK DIAGRAM



## MIPI60 to TI14 PIN ADAPTER



MIPI60 TO cTI 20 PIN ADAPTER




# HARDWARE SCHEMATICS

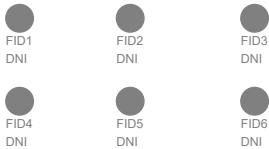
## ASSEMBLY NOTES

- 1. All MSL components should be baked as per JEDEC standard.
- 2. PCB should be baked at 120 degree for 8 hours.
- 3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
- 4. These assemblies are ESD sensitive, ESD precautions shall be observed.
- 5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 6. Provide serial numbers to the assembled boards for identification.
- 7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

## BARE PCB

PCB1  
  
PROC081A

## FIDUCIALS



## LOGOs

PCB  
LOGO  
DNI

PCB  
LOGO  
DNI

PCB  
LOGO  
DNI

For Evaluation only; not FCC approved for resale

WEEE Mark

CE Mark